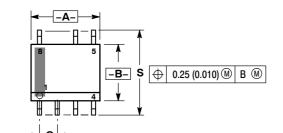
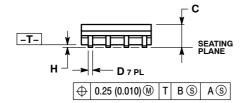
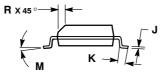


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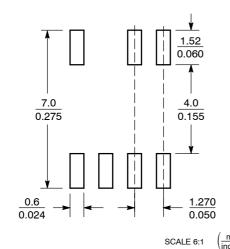
**DATE 20 OCT 2009** 







### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A AND B ARE DATUMS AND T IS A DATUM SURFACE.
  4. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
  5. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27	7 BSC	0.050 BSC	
Н	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0 244

### **GENERIC MARKING DIAGRAM**



XXX = Specific Device Code = Assembly Location Α

= Wafer Lot = Year = Work Week W = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

# **STYLES ON PAGE 2**

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## DATE 20 OCT 2009

STYLE 1: PIN 1. EMITTER 2. COLLECTOR 3. COLLECTOR 4. EMITTER 5. EMITTER 6. 7. NOT USED 8. EMITTER	3. COLLECTOR, #2 4. COLLECTOR, #2 5. BASE, #2 6. EMITTER, #2	<ol> <li>DRAIN, #1</li> <li>DRAIN, #2</li> </ol>
<ul><li>6. ANODE</li><li>7. NOT USED</li></ul>	PIN 1. DRAIN 2. DRAIN 3. DRAIN 4. DRAIN 5. 6.	STYLE 6: PIN 1. SOURCE 2. DRAIN 3. DRAIN 4. SOURCE 5. SOURCE 6. 7. NOT USED 8. SOURCE
STYLE 7: PIN 1. INPUT 2. EXTERNAL BYPASS 3. THIRD STAGE SOURCE	2. BASE (DIE 1)	STYLE 9: PIN 1. EMITTER (COMMON) 2. COLLECTOR (DIE 1) 3. COLLECTOR (DIE 2) 4. EMITTER (COMMON)
<ol> <li>GROUND</li> <li>DRAIN</li> <li>GATE 3</li> <li>NOT USED</li> <li>FIRST STAGE Vd</li> </ol>	3. BASE (DIE 2) 4. COLLECTOR (DIE 2) 5. COLLECTOR (DIE 2) 6. EMITTER (DIE 2) 7. NOT USED 8. COLLECTOR (DIE 1)	5. EMITTER (COMMON) 6. BASE (DIE 2) 7. NOT USED 8. EMITTER (COMMON)

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98AON12199	D

#### PAGE 2 OF 2

ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ. BY M. JONES	14 NOV 2002
Α	REPLACED ALL PIN 7 IN STYLES WITH "NOT USED". REQ BY M. JONES	06 DEC 2002
В	ADMINISTRATIVE CHANGE	07 JAN 2003
С	CORRECTED DIMENSIONS K AND H. REQ. BY M. JONES	03 JAN 2005
D	CORRECTED DEVICE MARKING INFORMATION FROM "AYWW" TO ALYW". ADDED PIN 1 BARS TO DIAGRAMS. REQ. BY S. BROW.	25 MAY 2007
Е	ADDED SOLDER FOOTPRINT. REQ. BY D. BRIGGS.	20 OCT 2009

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Case Outline Number: October, 2009 - Rev. 01E 751U